



Material Content Data Sheet



Sales Product Name		IPB100N04S3-03		Issued		29. August 2013			
MA#		MA000363376							
Package		PG-TO263-3-2		Weight*		1466.57 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.313	0.57	0.57	5669	5669	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174		
	non noble metal	copper	7440-50-8	851.691	58.06	58.14	580740	581495	
wire	non noble metal	aluminium	7429-90-5	11.688	0.80	0.80	7970	7970	
encapsulation	organic material	carbon black	1333-86-4	8.672	0.59		5913		
	plastics	epoxy resin	-	95.392	6.50		65044		
	inorganic material	silicondioxide	60676-86-0	474.069	32.33	39.42	323251	394208	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6585	6585	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.144	0.01		98		
	non noble metal	tin	7440-31-5	0.115	0.01		78		
	non noble metal	lead	7439-92-1	5.487	0.37	0.39	3741	3917	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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